40 V, 2.0 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	-40	Vdc
Collector-Base Voltage	V _{CBO}	-40	Vdc
Emitter-Base Voltage	V _{EBO}	-7.0	Vdc
Collector Current – Continuous	I _C	-2.0	Adc
Collector Current – Peak	I _{CM}	-4.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 1)	875 7.0	mW mW/°C
Thermal Resistance, Junction–to–Ambient	R _{θJA} (Note 1)	143	°C/W
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 2)	1.5 11.8	W mW/°C
Thermal Resistance, Junction–to–Ambient	R _{θJA} (Note 2)	85	°C/W
Thermal Resistance, Junction–to–Lead #1	R _{θJL} (Note 2)	23	°C/W
Total Device Dissipation (Single Pulse < 10 sec)	P _{Dsingle} (Notes 2 & 3)	3.0	W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

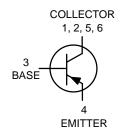
- 1. FR-4 @ 100 mm², 1 oz copper traces.
- 2. FR-4 @ 500 mm², 1 oz copper traces.
- Thermal response.

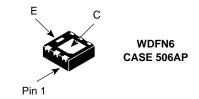


ON Semiconductor®

http://onsemi.com

-40~VOLTS 2.0~AMPS PNP LOW $\text{V}_{\text{CE(sat)}}$ TRANSISTOR EQUIVALENT $\text{R}_{\text{DS(on)}}$ 100 $\text{m}\Omega$





MARKING DIAGRAM

1 VA M 6 5 4

VA = Specific Device Code

1 = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40200UW6T1G	WDFN6 (Pb-Free)	3000/ Tape & Reel
NSV40200UW6T1G	WDFN6 (Pb-Free)	3000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS	·				
Collector – Emitter Breakdown Voltage (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-40	_	_	Vdc
Collector – Base Breakdown Voltage (I _C = -0.1 mAdc, I _E = 0)	V _(BR) CBO	-40	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	-7.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = -40 Vdc, I _E = 0)	I _{CBO}	-	-	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -7.0 Vdc)	I _{EBO}	-	-	-0.1	μAdc
ON CHARACTERISTICS			*		
DC Current Gain (Note 4) $ \begin{aligned} &(I_C = -10 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -2.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{aligned} $	h _{FE}	150 150 150 150	- - - -	- - - -	
Collector – Emitter Saturation Voltage (Note 4) ($I_C = -0.1 \text{ A}$, $I_B = -0.010 \text{ A}$) (Note 5) ($I_C = -1.0 \text{ A}$, $I_B = -0.100 \text{ A}$) ($I_C = -1.0 \text{ A}$, $I_B = -0.010 \text{ A}$) ($I_C = -2.0 \text{ A}$, $I_B = -0.020 \text{ A}$)	V _{CE(sat)}	- - - -	- -0.100 - -	-0.020 -0.120 -0.200 -0.300	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V _{BE(sat)}	-	-0.76	-0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I _C = -2.0 A, V _{CE} = -3.0 V)	V _{BE(on)}	-	-0.80	-0.900	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	140	-	-	MHz
Input Capacitance (V _{EB} = -0.5 V, f = 1.0 MHz)	Cibo	_		500	pF
Output Capacitance ($V_{CB} = -3.0 \text{ V}, f = 1.0 \text{ MHz}$)	Cobo	_		100	pF
SWITCHING CHARACTERISTICS	·				
Delay ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _d	-	-	70	ns
Rise ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	-	-	150	ns
Storage ($V_{CC} = 30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _s	-	-	525	ns
Fall ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _f	_	_	155	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.

5. Guaranteed by design but not tested.

TYPICAL CHARACTERISTICS

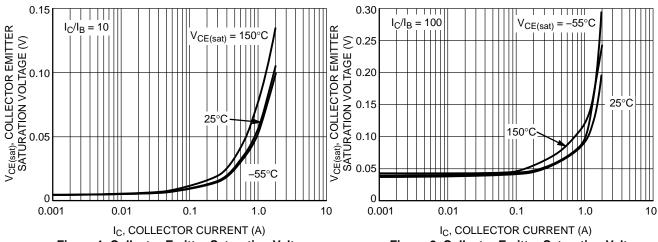
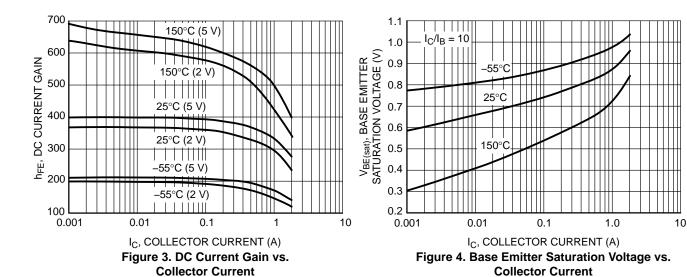


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current



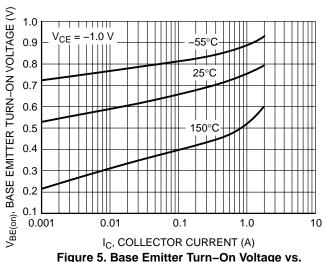


Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

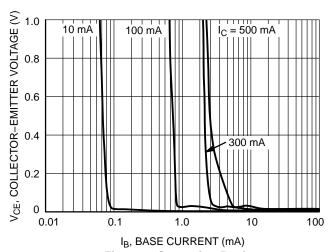
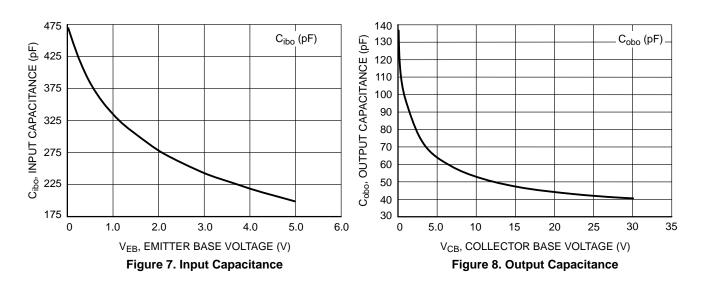


Figure 6. Saturation Region

TYPICAL CHARACTERISTICS



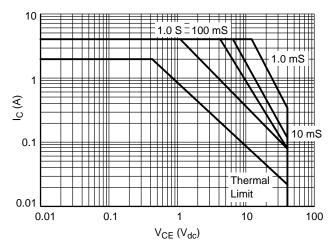
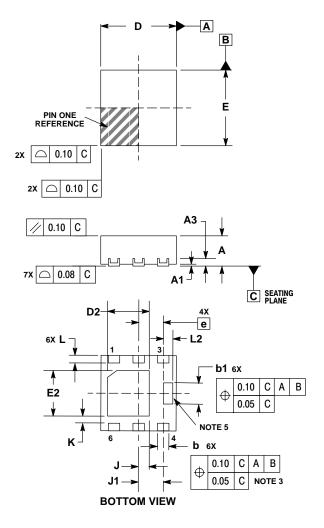


Figure 9. PNP Safe Operating Area

PACKAGE DIMENSIONS

WDFN6 2x2 CASE 506AP **ISSUE B**



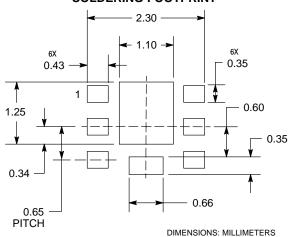
NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20mm FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

 5. CENTER TERMINAL LEAD IS OPTIONAL. TERMINAL
- LEAD IS CONNECTED TO TERMINAL LEAD # 4.
- 6. PINS 1, 2, 5 AND 6 ARE TIED TO THE FLAG.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.70	0.80	
A1	0.00	0.05	
A3	0.20	REF	
b	0.25	0.35	
b1	0.51	0.61	
D	2.00 BSC		
D2	1.00	1.20	
E	2.00 BSC		
E2	1.10	1.30	
е	0.65 BSC		
K	0.15 REF		
L	0.20	0.30	
L2	0.20	0.30	
J	0.27 REF		
J1	0.65 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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